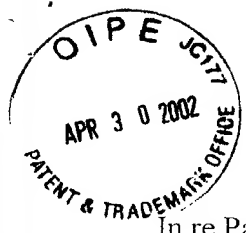


2827

COPY OF PAPERS
ORIGINALLY FILED



IR-1881 (2-2532)

#6/A
T.BELL
5.9.02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Bharat Shivkumar et al. ✓

Date: April 22, 2002

Serial No.: 09/812,027 ✓

Group Art Unit: 2827

Filed: March 19, 2001

Examiner: J.M. Mitchell

For: SEMICONDUCTOR MULTICHIP MODULE PACKAGE WITH IMPROVED
THERMAL PERFORMANCE, REDUCED SIZE AND IMPROVED MOISTURE
RESISTANCE

Asst. Commissioner for Patents
Washington, D.C. 20231

AMENDMENT/SUBMISSION

This is a response to the Office Action mailed March 28, 2002 in the above-identified application. Reconsideration of the application is respectfully requested.

RECEIVED
MAY -2 2002
TECHNOLOGY CENTER 2830

FEE CALCULATION

Any additional fee required has been calculated as follows:

_____ If checked, "Small Entity" status is claimed.

	NO. CLAIMS AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR		EXTRA PRESENT	RATE	ADDIT. FEE
TOTAL	15	MINUS	20	* =	X	(\$9 SE or \$18)	\$
INDEP.	3	MINUS	3	** =	X	(\$42 SE or \$84)	\$
FIRST PRESENTATION OF MULTIPLE DEPENDENT CLAIM						X (\$140 SE or \$280)	\$

* not less than 20 ** not less than 3 TOTAL \$

If any additional payment is required, a check which includes the calculated fee of \$ _____
(OFGS Check No. _____) is attached.